



DOCKET NO. R. ADDINALL 1-1

PATENT

2814
B100

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Ross Addinall, et al.

Serial No.: 09/639,288

Filed: August 15, 2000

For: INTEGRATED CIRCUIT DIE FOR WIRE BONDING
AND FLIP-CHIP MOUNTING

Group: 2814

Examiner: Cao, Phat X.

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313, on
09/22/2005 (Date)
Suphane P. H.
(Printed or typed name of person signing the certificate)
Suphane P. H.
(Signature of the person signing the certificate)

Sir:

DRAWING AMENDMENT UNDER 37 C.F.R. § 1.121

The attached sheets of drawings are formal drawings to replace the informal drawings initially filed with the above-identified application.

Attachment: Replacement Sheets 1-2.